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微波工程講義

Microwave Engineering Notes

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General Information

Scopes: microwave basics, principles of passive and active microwave components, microwave communication applications from electronic circuits point of view

Textbook: Radio-frequency and microwave communication circuits analysis and design, D.K.

Misra, John Wiley, 2001, 全華代理

Contents:

Ch.1 Introduction

Ch.2 Communication systems

Ch.3 Transmission lines

Ch.4 Resonant circuits

Ch.5 Impedance matching networks

Ch.6 Impedance transformers

Ch.7 Two-port networks

Ch.8 Filter design

Ch.9 Signal-flow graphs and applications

Ch.10 Transistor amplifier design

Ch.11 Oscillator design

Ch.12 Detectors and mixers

Grading policy: Midterm: 40%, final: 40%, homework: 20%

References:

1. Collin, R.E., Foundations for Microwave Engineering, McGraw Hill, 1992.
2. Pozar, D.M., Microwave Engineering, John Wiley, 2/e, 1998.

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Chapter 1 Introduction

- ◆ General description of microwaves
 - ✓ Related history,
 - ✓ Frequency bands,
 - ✓ Factors favor for RF and microwaves,
 - ✓ Propagation,
 - ✓ Passive and active devices,
 - ✓ Applications

1.1 Microwave transmission lines

General description of microwaves

1. Related history

• 19th century

1846 - earliest talk on EM wave, “Thoughts on ray vibrations,” Michael Faraday (1791-1867)

1864 - “Maxwell’s equations,” James Clark Maxwell (1831-1879)

1887 - first microwave-like experiment, “electric spark at $\lambda \sim 10\text{cm}$ induces at a distant wire loop,” Heinrich Rudolf Hertz (1857-1894)

1895 - wireless telegraphic communication and 1900 trans-Atlantic Ocean telegraph, Guglielmo Marconi (1874-1937)

• 20th century

1921 - magnetron, A. W. Hull

1930 - wave propagation in waveguide, George C. Southworth

1937 - klystron, Russell Varian, Sigurd Varian and William Hansen World War II – radar, MIT Radiation Laboratory

~1950 - coaxial cables for radio communication

~1960 - satellite communication

~1980 - remote sensing satellite, DBS (direct broadcast satellite)

~1990 - PCN/PCS (personal communications network/personal communication services), GPS (global positioning system), VSAT (very small aperture terminals)

~2000 - Digital DBS, WLL (wireless local loop), GII (global information initiative) using mobile satellite network, fibers, cables and wireless

- *IEEE Transactions on Microwave Theory and Techniques*, vol.32, no.9, Sept. 1984

2. Frequency bands

- Commercial broadcasting

	channels	frequency (Hz)	wavelength
AM	(US)107 (TW)133	535~1605K 522~1710K	186.92~560.75m
TV(VHF)	2-4	54~72M	4.7~5.56m
	5-6	76~88M	3.41~3.95m
FM	100	88~108M	2.78~3.41m
TV(UHF)	7-13	174~216M	1.39~1.72m
	14-83	470~890M	33.7~63.83cm

- RF band

band	frequency(Hz)	wavelength
VLF	3~30K	10~100km
LF	30~300K	1~10km
MF	300K~3M	100m~1km
HF	3~30M	10~100m
VHF	30~300M	1~10m
UHF	300M~3G	10cm~1m
SHF	3~30G	1cm~10cm
EHF	30~300G	0.1cm~1cm



microwaves

• Microwave band

band	frequency (GHz)	waveguide dimensions * (in.)	cutoff frequency (GHz)
UHF	0.5~1	18×9, WR-1800, 0.41-0.62GHz	0.33
		15×7.5, WR-1500, 0.49-0.75GHz	0.39
		11.5×5.75, WR-1150, 0.64-0.98GHz	0.51
L	1~2	7.7×3.85, WR-770, 0.96-1.46GHz	0.77
		6.5×3.25, WR-650, 1.74-1.73GHz	0.91
		5.1×2.55, WR-510, 1.45-2.2GHz	1.16
S	2~4	4.3×2.15, WR-430, 1.72-2.61GHz	1.37
		3.4×1.7, WR-340, 2.17-3.3GHz	1.74
		2.84×1.34, WR-284, 2.6-3.95	2.08
C	4~8	1.87×0.872, WR-187, 3.94-5.99GHz	3.15
		1.372×0.622, WR-137, 5.38-8.17GHz	4.3
X	8~12.4	0.9×0.4, WR-90	6.57
Ku	12.4~18	0.622×0.311, WR-62	9.49
K	18~26.5	0.42×0.17, WR-42	14.08
Ka	26.5~40	0.28×0.14, WR-28	21.2

* p562, table A3.3

3. Factors favor to microwaves

- antenna size

as antenna size $\sim \lambda$, it radiates efficiently

→ $f \uparrow$, $\lambda \downarrow$, size \downarrow , radiation efficiency \uparrow

- channel bandwidth

as $f \uparrow$ available spectrum bandwidth \uparrow

→ $f \uparrow$ for wider information bandwidth transmission, especially digital video transmission

e.g.,

1% BW of AM radio @1MHz gives 1 channel of 10kHz audio bandwidth

0.1% BW of C-band satellite communication @6GHz gives 1 channel of 6MHz video bandwidth

- propagation through atmosphere

ground wave (LF band, 30-300KHz) travels over and near the earth surface

→ ground absorption loss, especially for h-polarization

→ AM radio uses vertical polarization,

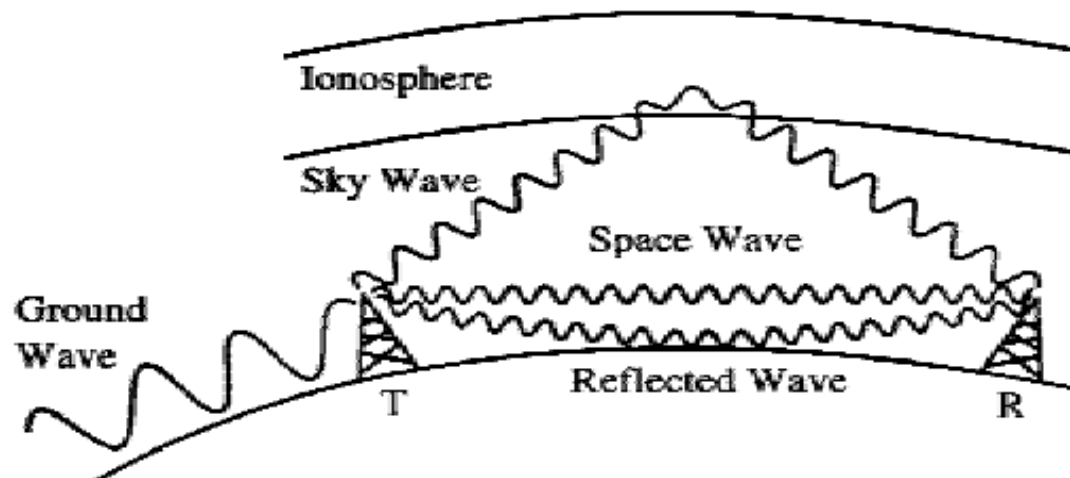
sky wave (HF band, 3-30MHz) performs refraction (signal bending) in ionosphere,

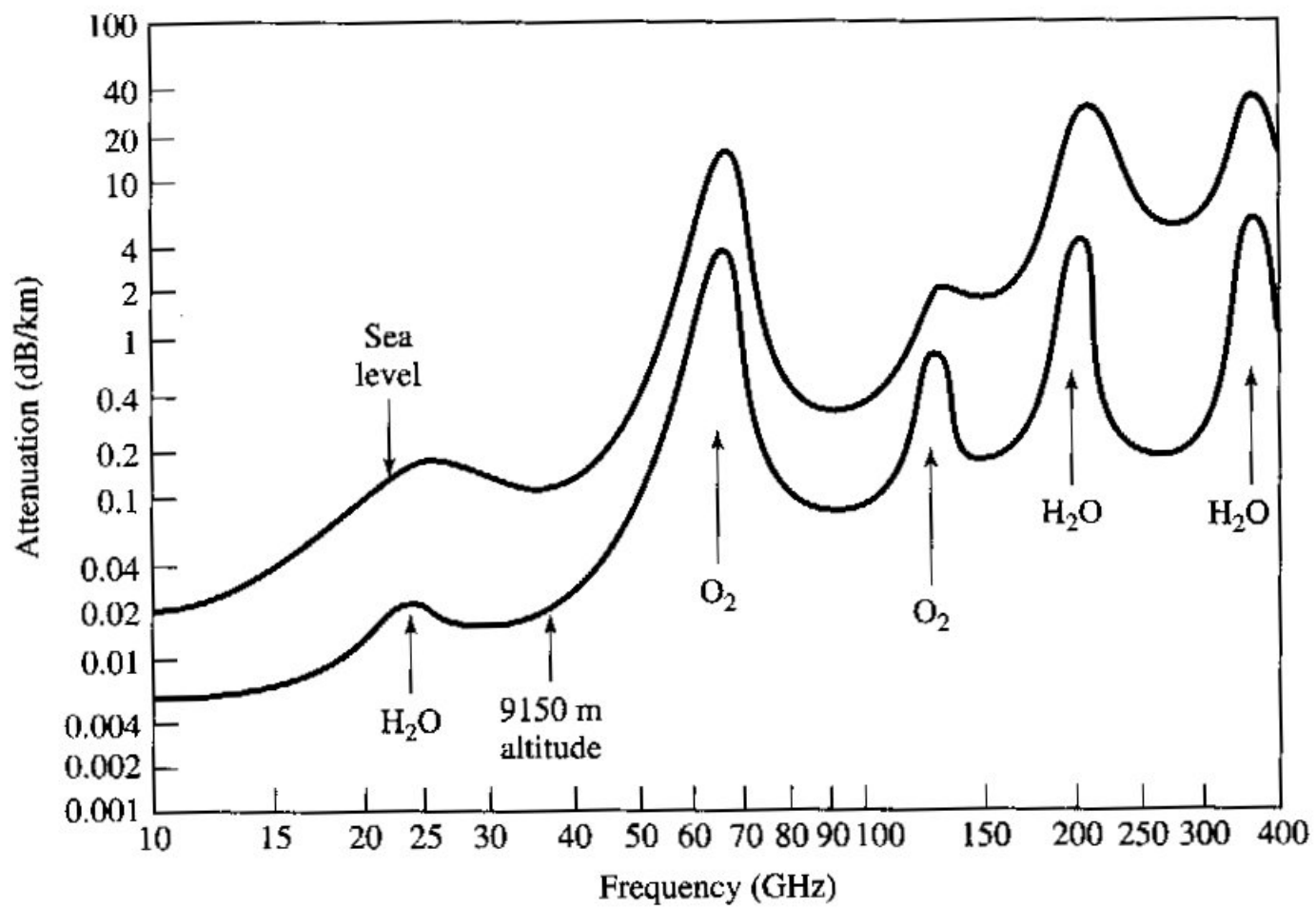
plasma frequency $\sim 9\text{MHz}$ → short-wave radio

space wave (VHF, UHF and microwave, 30M-300GHz) direct wave (line-of sight, LOS) and reflected wave → interference or multi-path phenomenon

low atmospheric attenuation and unaffected by rain and cloud

→ wireless, mobile, terrestrial and satellite communication





4. Microwave devices

- In general, input/output matching is inherently required for microwave components over the operating band.
- passive devices (without DC bias)
diplexer, filter, coupler, power divider/combiner, isolator, circulator, attenuator, adapter, terminator, cable, transmission line, waveguide, resonator, detector, mixer, phase shifter, lumped R, L, C, antenna,...
- active devices (with DC bias)
amplifier, oscillator, switch, mixer, frequency multiplier, active antenna,
- vacuum tube devices

linear beam type		cross-field type
EM cavity type	slow-wave circuit type	
klystron amplifier, oscillator	TWT (traveling wave tube) amplifier	magnetron

• Solid-state devices

junction effect	field effect	transfer electron	avalanche effect	lasing effect
BJT	JFET	Gunn diode	IMPATT diode	laser mixing
HBT	MESFET	LSA diode	TRAPATT diode	maser
Tunnel diode	HEMT	InP diode	BARITT diode	
Schottky-barrier diode	MOSFET	CdTe diode	parametric devices	
PIN diode	NMOS, PMOS, CMOS			

HBT: heterojunction bipolar transistor

MESFET: metal-semiconductor field-effect transistor

HEMT: high electron mobility transistor

MOSFET: metal-oxide-semiconductor field-effect transistor

CMOS: complementary metal-oxide-semiconductor transistor

IMPATT diode: impact ionization avalanche transit-time diode

TRAPATT diode: trapped plasma avalanche triggered transit-time diode

BARITT diode: barrier injected transit-time diode

maser: microwave amplification by stimulated emission of radiation

LSA diode: limited space-charge accumulation mode of the Gunn diode

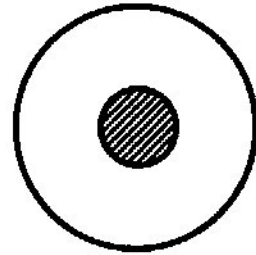
- Vacuum tube technology finds its applications in high power (W-MW) and high frequency (200MHz-200GHz)
e.g., magnetron: kW CW source in microwave oven, MW pulsed source in radar, traveling wave tube amplifier: >10 W power amplifier in satellite, klystron: local oscillator in receiver.
- Microwave solid-state devices are low cost, low power supply, low noise, small, light weight, easy cooling, reliable and long life time compared with microwave tubes.

5. Microwave applications

communication	radar		industrial, scientific and biomedical
	civilian	military	
Broadcasting WLAN Cordless phone RFID Cellular Terrestrial Satellite GPS	air traffic control, aircraft navigation, ship safety, law enforcement	surveillance, navigation, weapon guidance, electronic warfare C ³ I (command, control, communication, information)	drying, curing, heating, cooking process control, imaging, hyperthermia, patient monitoring, remote sensing radio astronomy, power transmission ,particle acceleration

- Growth and expansion of microwave technology move from military and satellite applications into information and entertainment applications.

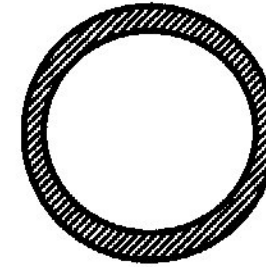
1.1 Microwave transmission lines



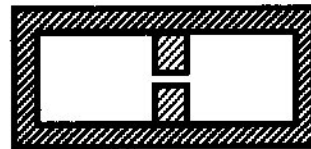
(a) Coaxial line



(b) Rectangular waveguide



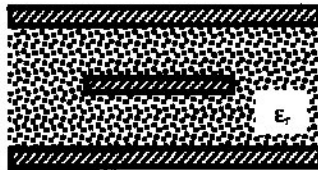
(c) Circular waveguide



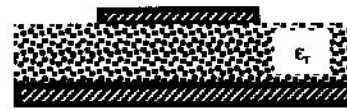
(d) Ridged waveguide



(e) Fin line



(f) Strip line



(g) Microstrip line



(h) Slot line

Figure 1.6 Transmission lines used in RF and microwave circuits.

	coaxial line	waveguide	microstrip
mode: preferred	TEM	TE ₁₀	quasi-TEM
other	TM, TE	TM, TE	Hybrid TM, TE
dispersion	none	medium	low
bandwidth	high	low	high
loss	medium	low	high
power capacity	medium	high	low
physical size	large	large	small
easy of fabrication	medium	medium	easy
integration with other components	hard	hard	easy